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JUNG et al.(10) **Pub. No.: US 2012/0242222 A1**(43) **Pub. Date: Sep. 27, 2012**(54) **ORGANIC LIGHT EMITTING DIODE
DISPLAY****Publication Classification**(51) **Int. Cl.**
H01L 51/52 (2006.01)(52) **U.S. Cl.** **313/512**(57) **ABSTRACT**

An OLED display may include: a substrate; an organic light emitting diode on the substrate; a thin film encapsulation layer encapsulates the organic light emitting diode with the substrate; an optical film on the thin film encapsulation layer and including an adhesive layer opposite to the thin film encapsulation layer; and a contamination preventing layer between the thin film encapsulation layer and the optical film, the contamination preventing layer contacting the adhesive layer.

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Yongin-City (KR)(21) Appl. No.: **13/298,697**(22) Filed: **Nov. 17, 2011**(30) **Foreign Application Priority Data**

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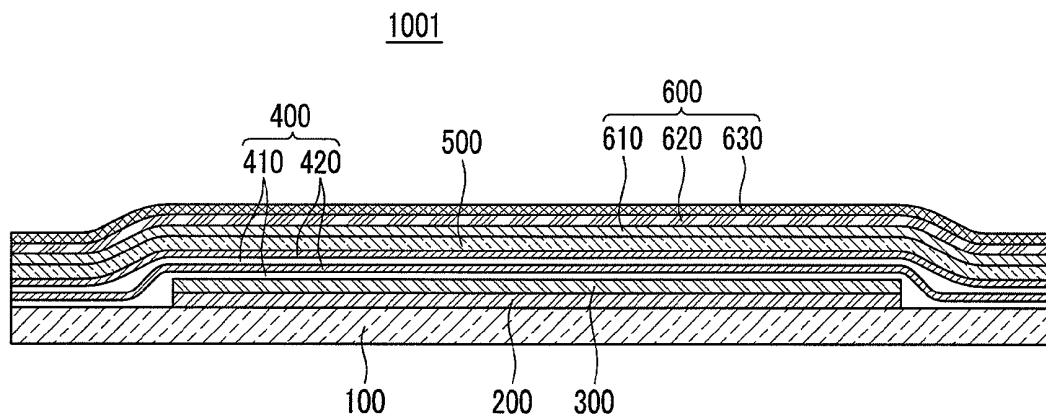


FIG.1

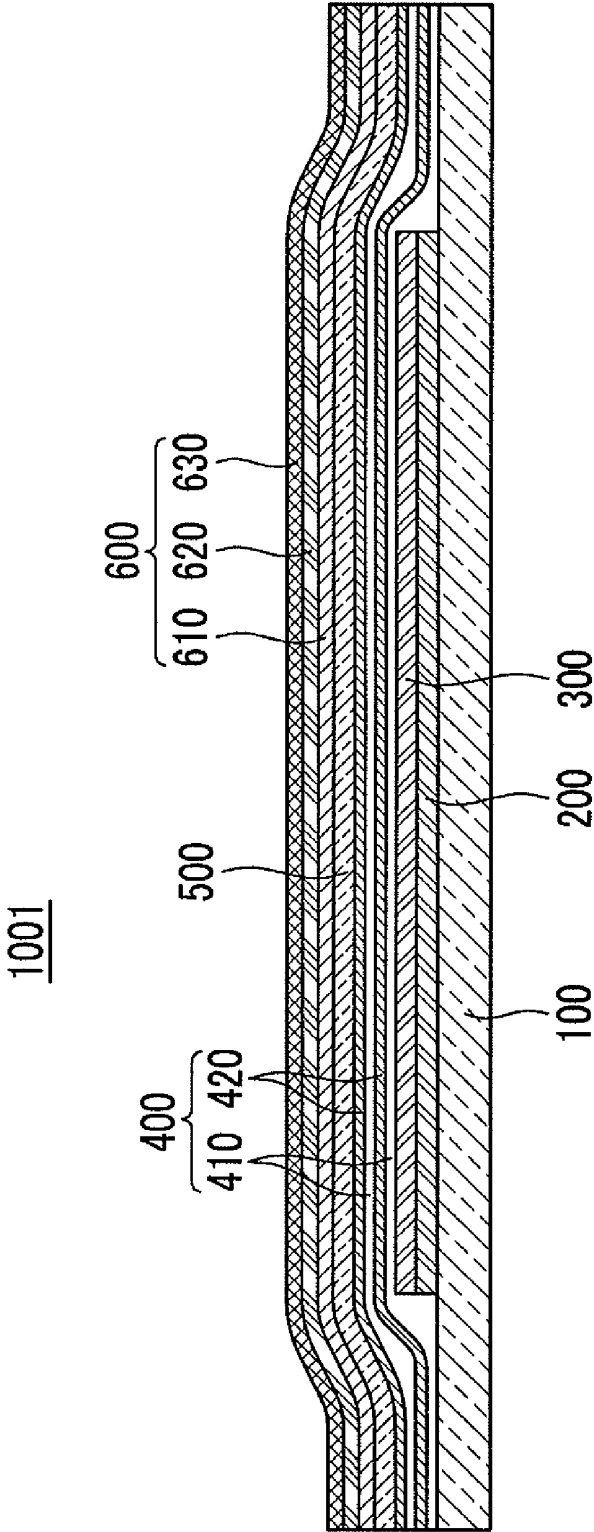


FIG. 3

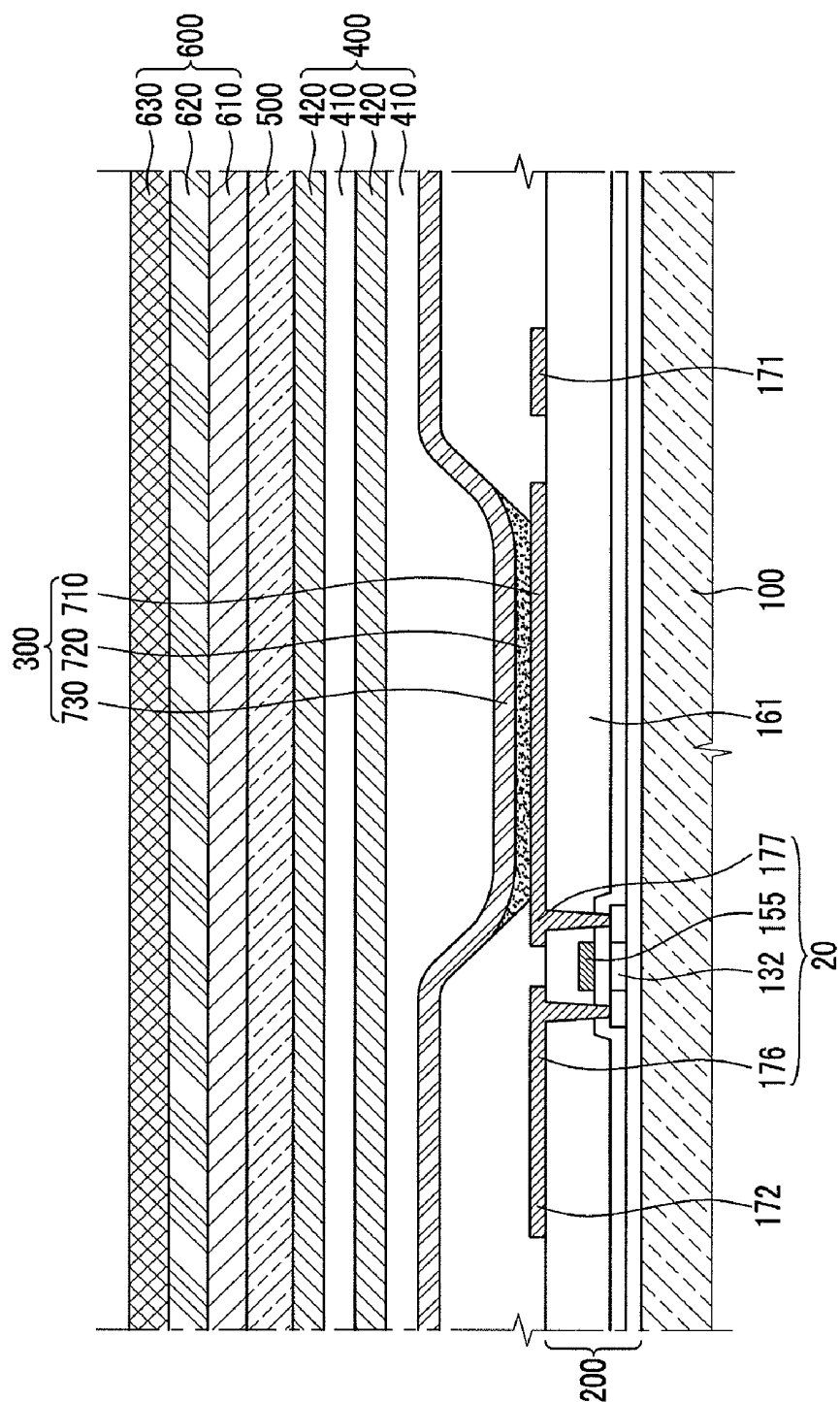
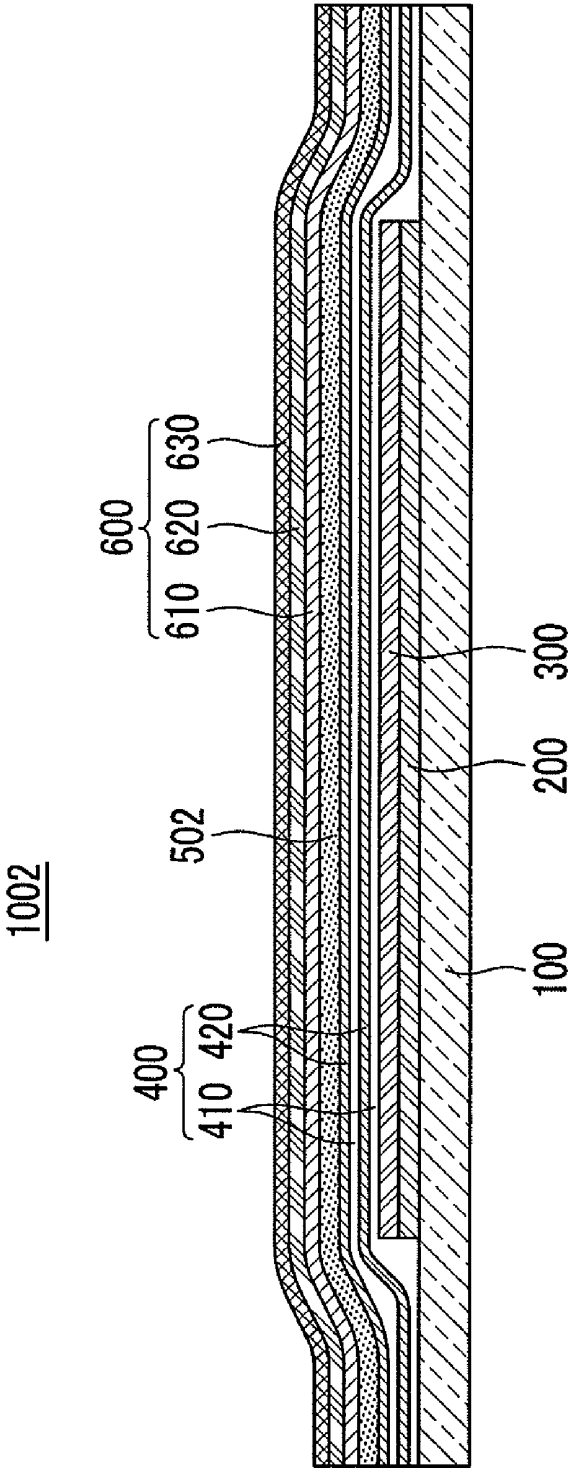


FIG.4



ORGANIC LIGHT EMITTING DIODE DISPLAY

RELATED APPLICATIONS

[0001] This application claims priority to and the benefit of Korean Patent Application No. 10-2011-0026576 filed in the Korean Intellectual Property Office on Mar. 24, 2011, the entire contents of which are incorporated herein by reference.

BACKGROUND

[0002] 1. Field

[0003] Embodiments relate generally to an organic light emitting diode (OLED) display. More particularly, embodiments relate to an OLED display using a thin film encapsulation layer as an encapsulation member.

[0004] 2. Description of the Related Art

[0005] An organic light emitting diode display, which is a device displaying an image, has recently attracted attention.

[0006] The organic light emitting diode display has a self-emitting characteristic and does not need a separate light source. Thus, the thickness and weight of an organic light emitting diode display are lower than a liquid crystal display. In addition, the organic light emitting diode display has high-grade characteristics, i.e., low power consumption, high luminance, high reaction speed, etc.

[0007] In general, the organic light emitting diode display includes a substrate, an organic light emitting diode disposed on the substrate and displaying an image, and an encapsulation member arranged opposite to the substrate, interposing the organic light emitting diode therebetween, and encapsulating the organic light emitting diode.

[0008] The above information in the Background is only for enhancing an understanding of the described technology. Therefore, it may contain information that does not form the prior art known to a person of ordinary skill in the art in this country.

SUMMARY

[0009] Embodiments are directed to an organic light emitting diode (OLED) display.

[0010] An embodiment may be directed to an OLED display including: a substrate; an organic light emitting diode on the substrate; a thin film encapsulation layer encapsulating the organic light emitting diode with the substrate; an optical film on the thin film encapsulation layer and including an adhesive layer arranged opposite to the thin film encapsulation layer; and a contamination preventing layer between the thin film encapsulation layer and the optical film, the contamination preventing layer contacting the adhesive layer.

[0011] A surface of the contamination preventing layer contacting the adhesive layer may be more hydrophobic than the thin film encapsulation layer.

[0012] The surface of the contamination preventing layer may have a contact angle of about 100 to 200 degrees with respect to water.

[0013] The contamination preventing layer may include fluorine (F).

[0014] The contamination preventing layer may have weaker adherence compared to the adhesive layer.

[0015] The optical film may include a polarization film.

[0016] The thin film encapsulation layer may include an inorganic layer contacting the contamination preventing layer.

BRIEF DESCRIPTION OF THE DRAWINGS

[0017] FIG. 1 shows an organic light emitting diode display according to a first exemplary embodiment.

[0018] FIG. 2 is a layout view of a pixel structure of the organic light emitting diode display according to the first exemplary embodiment.

[0019] FIG. 3 is a cross-sectional view of FIG. 2, taken along the line III-III.

[0020] FIG. 4 shows an organic light emitting diode display according to a second exemplary embodiment.

DETAILED DESCRIPTION

[0021] Example embodiments will now be described more fully hereinafter with reference to the accompanying drawings; however, they may be embodied in different forms and should not be construed as limited to the embodiments set forth herein.

[0022] In order to elucidate present embodiments, parts that are not related to the description will be omitted. Like reference numerals designate like elements throughout the specification.

[0023] In addition, the size and thickness of each component shown in the drawings are arbitrarily shown for understanding and ease of description, but present embodiments are not limited thereto.

[0024] In the drawings, the thickness of layers, films, panels, regions, etc., are exaggerated for clarity. In addition, in the drawings, for understanding and ease of description, the thicknesses of some layers and areas are exaggerated. It will be understood that when an element such as a layer, film, region, or substrate is referred to as being "on" another element, it can be directly on the other element or intervening elements may also be present.

[0025] In addition, unless explicitly described to the contrary, the word "comprise" and variations such as "comprises" or "comprising" will be understood to imply the inclusion of stated elements but not the exclusion of any other elements. Further, throughout the specification, "on" implies being positioned above or below a target element and does not imply being necessarily positioned on the top on the basis of a gravity direction.

[0026] Hereinafter, an organic light emitting diode (OLED) display according to a first exemplary embodiment will be described with reference to FIG. 1 to FIG. 3.

[0027] FIG. 1 shows an OLED display according to the first exemplary embodiment.

[0028] As shown in FIG. 1, an OLED display 1001 according to the first exemplary embodiment includes a substrate 100, a wiring portion 200, an organic light emitting diode 300, a thin film encapsulation layer 400, a contamination preventing layer 500, and an optical film 600.

[0029] The substrate 100 is formed with a material that may be light-transmissive, light-absorptive, or light-transflective. For example, the material may be glass, resin, or metal. The wiring portion 200 and the organic light emitting diode 300 are disposed on the substrate 100. The substrate 100 encapsulates the organic light emitting diode 300 with the thin film encapsulation layer 400 interposing the wiring portion 200 and the organic light emitting diode 300 therebetween. The

substrate **100** and the thin film encapsulation layer **400** protect the wiring portion **200** and the organic light emitting diode **300** from external interference. The substrate **100** may have flexibility, and the thin film encapsulation layer **400** is formed in a thin film such that the OLED display **1001** has flexibility.

[0030] The wiring portion **200** includes first and second thin film transistors **10** and **20** (shown in FIG. 2), and drives the organic light emitting diode **300** by transmitting a signal to the organic light emitting diode **300**. The organic light emitting diode **300** emits light according to the signal transmitted from the wiring portion **200** to display an image.

[0031] The organic light emitting diode **300** is disposed on the wiring portion **200**.

[0032] The organic light emitting diode **300** is disposed on the substrate **100**, and displays an image by emitting light by the signal transmitted from the wiring portion **200**.

[0033] An internal structure of the OLED display **1001** according to the first exemplary embodiment will now be described in further detail with reference to FIG. 2 and FIG. 3.

[0034] FIG. 2 is a layout view of a pixel structure of the OLED display according to the first exemplary embodiment. FIG. 3 is a cross-sectional view of FIG. 2, taken along the line III-III.

[0035] The entire structure of the wiring portion **200** and the organic light emitting diode **300** are shown in FIG. 2 and FIG. 3, but the present exemplary embodiment is not limited to the structure shown in FIG. 2 and FIG. 3. The structure of the wiring portion **200** and the organic light emitting diode **300** may be variously modified by a person skilled in the art. For example, in the accompanying drawing, an active matrix (AM) organic light emitting diode display having a 2T1C structure that includes two thin film transistors (TFTs) **10** and **20** and one capacitor **80** in one pixel is shown as an OLED display, but present embodiments are not limited thereto. Thus, the number of thin film transistors, the number of capacitors, and the number of wires of the OLED display is not restrictive. The pixel represents a minimum unit displaying an image, and the OLED displays an image using a plurality of pixels.

[0036] As shown in FIG. 2 and FIG. 3, the OLED display **1001** includes a switching thin film transistor **10**, a driving thin film transistor **20**, a capacitor **80**, and an organic light emitting diode **300** formed in each pixel. Here, a configuration including the switching thin film transistor **10**, the driving thin film transistor **20**, and the capacitor **80** forms the wiring portion **200**. In addition, the wiring portion **200** further includes gate lines **151** arranged along one direction of the substrate **100**, data lines **171**, and common power lines **172**. The data lines **171** and the common power lines **172** cross the gate lines **151** in an insulated manner. Here, one pixel may be defined by the boundary of the gate line **151**, the data line **171**, and the common power line **172**, but present embodiments are not limited thereto.

[0037] The organic light emitting diode **300** includes a first electrode **710**, an organic emission layer **720** formed on the first electrode **710**, and a second electrode **730** formed on the organic emission layer **720**. The first electrode **710**, organic emission layer **720**, and the second electrode **730** form the organic light emitting diode **300**. Here, the first electrode **710** becomes an anode, i.e., a hole injection electrode and the second electrode **730** becomes a cathode, i.e., an electron injection electrode. However, the exemplary embodiment is not limited thereto, and the first electrode **710** may become a

cathode and the second electrode **730** may become an anode according to a driving method of the OLED display. Holes and electrons are injected into the organic emission layer **720** respectively from the anode **710** and the cathode **730**. When an exciton, in which the hole and the electron injected into the organic emission layer **720** are coupled to each other, falls from an excited state to a ground state, light emission occurs. In addition, at least one of the first and second electrodes **710** and **730**, for example the second electrode **730**, may be formed in a light transmissive structure, and accordingly, the organic light emitting diode **300** emits light in a direction of the thin film encapsulation layer **400** to display an image.

[0038] The capacitor **80** includes a pair of capacitor plates **158** and **178** arranged interposing an interlayer insulating layer **161** therebetween. Here, the interlayer insulating layer **161** becomes a dielectric material, and capacitance of the capacitor **80** is determined by charges charged in the capacitor **80** and a voltage between the two capacitor plates **158** and **178**.

[0039] The switching thin film transistor **10** includes a switching semiconductor layer **131**, a switching gate electrode **152**, a switching source electrode **173**, and a switching drain electrode **174**. The driving thin film transistor **20** includes a driving semiconductor layer **132**, a driving gate electrode **155**, a driving source electrode **176**, and a driving drain electrode **177**.

[0040] The switching thin film transistor **10** is used as a switch to select a pixel for light emission. The switching gate electrode **152** is connected to the gate line **151**. The switching source electrode **173** is connected to the data line **171**. The switching drain electrode **174** is distanced from the switching source electrode **173** and is connected with the capacitor plate **158** of the two capacitor plates **158** and **178**.

[0041] The driving thin film transistor **20** applies driving power to the second electrode **730** for light emission of an organic emission layer **720** of an organic light emitting diode **300** of the selected pixel. The driving gate electrode **155** is connected with the capacitor plate **158** that is connected with the switching drain electrode **174**. The driving source electrode **176** and the other capacitor plate **178** are respectively connected with the common power line **172**. The driving drain electrode **177** is disposed at the same layer where the first electrode **710** is disposed, and is connected with the first electrode **710**.

[0042] In the OLED display according to the first exemplary embodiment, the driving drain electrode **177** and the first electrode **710** are disposed on the same layer, but a driving drain electrode of an OLED display according to another exemplary embodiment and a first electrode are disposed in different layers and may access the first electrode through an opening formed in an insulating layer.

[0043] With such a structure, the switching thin film transistor **10** is driven by a gate voltage applied to the gate line **151** to transmit a data voltage applied to the data line **171** to the driving thin film transistor **20**. A voltage corresponding to a difference between a common voltage applied to the driving thin film transistor **20** from the common power line **172** and the data voltage transmitted from the switching thin film transistor **10** is stored in the capacitor **80**, and a current corresponding to the voltage stored in the capacitor **80** flows to the organic light emitting diode **300** through the driving thin film transistor **20** such that the organic light emitting diode **300** emits light.

[0044] Referring to FIG. 1 and FIG. 3, the thin film encapsulation layer 400 encapsulates the organic light emitting diode 30 with the substrate 100, and includes a plurality of organic layers 410 and a plurality of inorganic layers 420 alternately arranged with each other.

[0045] The organic layer 410 is arranged opposite to the substrate 10, interposing the organic light emitting diode 300 therebetween, and seals the organic light emitting diode 300 by covering the same. The organic layer 410 has a weaker waterproofing property than the inorganic layer 420 but has flexibility so that the organic layer 410 reinforces weakness of the inorganic layer 420 having stronger rigidity than the organic layer 410, and may have a single-layered structure or a multi-layered structure including a resin such as polyethylene terephthalate (PET), polyimide (PI), and polycarbonate (PC).

[0046] In the OLED display 1001 according to the first exemplary embodiment, the organic layer 410 includes a resin including at least one of polyethylene terephthalate (PET), polyimide (PI), and polycarbonate (PC), but a resin layer of an OLED display according to another exemplary embodiment may be a single or multiple layer including an engineering plastic including at least one of glass fiber reinforced plastic (FRP), polyethylene terephthalate (PET), and polymethylmethacrylate (PMMA).

[0047] The inorganic layer 420 is disposed at the uppermost layer between neighboring organic layers 410 among the plurality of organic layers 410 and the thin film encapsulation layer 400 on the organic light emitting diode 300, and contacts the contamination preventing layer 500. The inorganic layer 420 seals the organic light emitting diode 300 and the organic layer 410 by covering the organic light emitting diode 300 and the organic layer 410. The inorganic layer 420 has an excellent waterproofing property compared to the organic layer 410. The inorganic layer 420 may be a single or multiple layer including at least one of silicon oxide (SiOx), silicon nitride (SiNx), titanium oxide (TiOx), an aluminum oxide such as alumina (Al₂O₃), and silicon oxide nitride.

[0048] In the OLED display 1001 according to the first exemplary embodiment, the thin film encapsulation layer 400 includes a plurality of organic layers 410 and a plurality of inorganic layers 420 that are alternately arranged with each other, but a thin film encapsulation layer of an OLED display according to another exemplary embodiment may include one organic layer 410 and one inorganic layer 420 sequentially layered on the organic light emitting diode or may include only an inorganic layer 420.

[0049] The contamination preventing layer 500 is disposed on the thin film encapsulation layer 400.

[0050] The contamination preventing layer 500 is disposed between the thin film encapsulation layer 400 and the optical film 600, and respectively contacts the thin film encapsulation layer 400 and an adhesive layer 610 of the optical film 600. The contamination preventing layer 500 is coated on the thin film encapsulation layer 400. As described, being coated on the thin film encapsulation layer 400, the contamination preventing layer 500 can prevent the thin film encapsulation layer 400 from being contaminated during a manufacturing process of the OLED display 1001 and simultaneously prevents the surface of the thin film encapsulation layer 400 from being damaged due to adherence of the adhesive layer 610 of the optical film 600 when a process is performed to detach the optical film 600 from the thin film encapsulation layer 400 to solve an adherence problem that may occur between the thin

film encapsulation layer 400 and the optical film 400 during the manufacturing process of the OLED display 1001.

[0051] Particularly, the inorganic layer 420 having the excellent waterproofing property compared to the organic layer 410 is disposed at the uppermost layer of the thin film encapsulation layer 400 for waterproofing of the organic light emitting diode 300. The inorganic layer 420 is made of a fragile material, e.g., a ceramic. Therefore, the inorganic layer 420 may be damaged due to adherence of the adhesive layer 610 of the optical film 600 when a process for detaching the optical film 600 from the thin film encapsulation layer 400 is performed. That is, the contamination preventing layer 500 is disposed between the thin film encapsulation layer 400 and the adhesive layer 610 of the optical film 600 in consideration of the fragility of the inorganic layer 420 disposed at the uppermost layer of the thin film encapsulation layer 400. Accordingly, the contamination preventing layer 500 can prevent damage to the inorganic layer 420 exposed to the surface of the thin film encapsulation layer 400 due to the adherence of the adhesive layer 610 of the optical film 600 during a process for detaching the optical film 600 from the thin film encapsulation layer 400.

[0052] Further, the surface of the contamination preventing layer 500 contacting the adhesive layer 610 of the optical film 600 is more hydrophobic than the inorganic layer 420 of the thin film encapsulation layer 400. More particularly, the surface of the contamination preventing layer 500 has a contact angle of about 100 to 200 degrees with respect to water. The contamination preventing layer 500 may include fluorine (F). For example, the contamination preventing layer 500 may include silica and perfluorinated acid (PFA), may include a siloxane group and a perfluoro group, or may include a fluorine-containing graft copolymer.

[0053] The optical film 600 is attached to the contamination preventing layer 500.

[0054] The optical film 600 is disposed on the thin film encapsulation layer 400, interposing the contamination preventing layer 500 therebetween, and includes an adhesive layer 610 attached to the contamination preventing layer 500 while being in contact with the contamination preventing layer 500. The optical film 600 suppresses reflection of external light irradiated to the OLED display 1001 to improve quality of an image displayed from the organic light emitting diode 300. The optical film 600 further includes a phase difference film 620 and a polarization film 630 sequentially attached on the adhesive layer 610 contacting the contamination preventing layer 500. Here, the phase difference film 620 can change the phase of light of 214, and the polarization film 630 can linearly polarize light.

[0055] As described, in the OLED display 1001 according to the first exemplary embodiment, the contamination preventing layer 500 contacting the optical film 600 has a hydrophobic surface. Accordingly, contamination of the thin film encapsulation layer 500 that may occur due to a liquid such as a washing solution that may be used during the manufacturing process of the OLED display 1001 can be prevented. Simultaneously, damage to the surface of the thin film encapsulation layer 400 that may occur due to adherence of the adhesive layer 610 of the optical film 600 when a process is performed to detach the optical film 600 from the thin film encapsulation layer 400 to solve an adherence problem that may occur between the thin film encapsulation layer 400 and the optical film 400 during the manufacturing process of the OLED display 1001 can be prevented because the adhesive layer 610

of the optical film 600 can be easily separated from the contamination preventing layer 500. This can improve the product yield of the OLED display 1001.

[0056] Hereinafter, an OLED display 1002 according to a second exemplary embodiment will be described with reference to FIG. 4.

[0057] Only characteristic parts of the OLED according to the second embodiment other than those of the OLED display according to the first embodiment are described, and undescribed parts will be appreciated referring to the OLED display according to the first embodiment. In addition, in the second exemplary embodiment, the same reference numerals refer to the same components as those of the OLED display according to the first embodiment, for better comprehension and ease of description.

[0058] FIG. 4 shows an OLED display 1002 according to the second exemplary embodiment.

[0059] As shown in FIG. 4, the OLED display 1002 according to the second exemplary embodiment includes the substrate 100, the wiring portion 200, the organic light emitting diode 300, the thin film encapsulation layer 400, the contamination preventing layer 502, and the optical film 600.

[0060] The contamination preventing layer 502 is disposed between the thin film encapsulation layer 400 and the optical film 600, and contacts the thin film encapsulation layer 400 and the adhesive layer 610 of the optical film 600. The contamination preventing layer 502 may be made of, for example, an acryl-based adhesive. The contamination preventing layer 502 is coated on the thin film encapsulation layer 400. As described, by being coated on the thin film encapsulation layer 400, the contamination preventing layer 502 can prevent the thin film encapsulation layer 400 from being contaminated during a manufacturing process of the OLED display 1002, and may simultaneously prevent the surface of the thin film encapsulation layer 400 from being damaged due to adherence of the adhesive layer 610 of the optical film 600 when a process is performed to detach the optical film 600 from the thin film encapsulation layer 400 to solve an adherence problem that may occur between the thin film encapsulation layer 400 and the optical film 400 during the manufacturing process of the OLED display 1002. Particularly, since the contamination preventing layer 502 has weaker adherence compared to the adhesive layer 610 of the optical film 610, the adhesive layer 610 of the optical film 600 is easily detached from the contamination preventing layer 502 when a process for detaching the optical film 600 from the thin film encapsulation layer 400 to solve an adherence failure between the thin film encapsulation layer 400 and the optical film 600 that may occur during a manufacturing process of the OLED display 1002 such than the optical film 600 is easily separated from the thin film encapsulation layer 400, thereby preventing damage to the surface of the thin film encapsulation layer 400 due to adherence of the adhesive layer 610 of the optical film 600. This can improve the product yield of the OLED display 1002.

[0061] By way of summation and review, an organic light emitting diode display has been developed using a thin film encapsulation layer as an encapsulation member.

[0062] However, the organic light emitting diode display attaches an optical film, i.e., a polarization plate to the thin film encapsulation layer to improve quality of an image displayed by the organic light emitting diode. When a process for detaching the optical film from the thin film encapsulation layer is performed to solve an adherence failure of the optical film with respect to the organic light emitting diode display, damage may occur to the surface of the thin film encapsulation layer. The damage may occur because of adherence of the optical film when the optical film is detached from the thin film encapsulation layer.

[0063] Embodiments are directed to an organic light emitting diode (OLED) display including a thin film encapsulation layer that encapsulates an organic light emitting diode. The OLED display may suppress damage to the surface of a thin film encapsulation layer during re-processing of an optical film attached to the thin film encapsulation layer.

[0064] Exemplary embodiments have been disclosed herein, and although specific terms are employed, they are used and are to be interpreted in a generic and descriptive sense only and not for purpose of limitation.

What is claimed is:

1. An organic light emitting diode (OLED) display, comprising:
 - a substrate;
 - an organic light emitting diode on the substrate;
 - a thin film encapsulation layer encapsulating the organic light emitting diode with the substrate;
 - an optical film on the thin film encapsulation layer and including an adhesive layer opposite to the thin film encapsulation layer; and
 - a contamination preventing layer between the thin film encapsulation layer and the optical film, the contamination preventing layer contacting the adhesive layer.
2. The OLED display as claimed in claim 1, wherein a surface of the contamination preventing layer contacting the adhesive layer is more hydrophobic than the thin film encapsulation layer.
3. The OLED display as claimed in claim 2, wherein the surface of the contamination preventing layer has a contact angle of about 100 to 200 degrees with respect to water.
4. The OLED display as claimed in claim 2, wherein the contamination preventing layer includes fluorine (F).
5. The OLED display as claimed in claim 1, wherein the contamination preventing layer has weaker adherence compared to the adhesive layer.
6. The OLED display as claimed in claim 1, wherein the optical film includes a polarization film.
7. The OLED display as claimed in claim 1, wherein the thin film encapsulation layer includes an inorganic layer contacting the contamination preventing layer.

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专利名称(译)	有机发光二极管显示器		
公开(公告)号	US20120242222A1	公开(公告)日	2012-09-27
申请号	US13/298697	申请日	2011-11-17
[标]申请(专利权)人(译)	JUNG禹锡 PARK SOON RYONG PARK惠姪		
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优先权	1020110026576 2011-03-24 KR		
其他公开文献	US8841840		
外部链接	Espacenet USPTO		

摘要(译)

OLED显示器可包括：基板;基板上的有机发光二极管;薄膜封装层将有机发光二极管封装在基板上;薄膜封装层上的光学薄膜，包括与薄膜封装层相对的粘合层;以及薄膜封装层和光学膜之间的防污染层，防污染层与粘合剂层接触。

